

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
RU-SHANG HSIAO	02/27/2014
LING-SUNG WANG	03/11/2014
CHIH-MU HUANG	02/27/2014
CING-YAO CHAN	03/03/2014
CHUN-YING WANG	03/04/2014
JEN-PAN WANG	02/27/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSIN-CHU SCIENCE PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14205911
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	216-502-0600
<b>Email:</b>	docketing@eschweilerlaw.com
<b>Correspondent Name:</b>	ESCHWEILER & ASSOCIATES, LLC.
<b>Address Line 1:</b>	629 EUCLID AVENUE, SUITE 1000
<b>Address Line 2:</b>	NATIONAL CITY BANK BUILDING
<b>Address Line 4:</b>	CLEVELAND, OHIO 44114
<b>ATTORNEY DOCKET NUMBER:</b>	TSMCP408US
<b>NAME OF SUBMITTER:</b>	DAVID W. POTASHNIK
<b>SIGNATURE:</b>	/David W. Potashnik/
<b>DATE SIGNED:</b>	04/01/2014

PATENT

**Total Attachments: 8**

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Filing Date

TSMC Docket No. TSMC2013-1556  
Docket No. TSMCP408US

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Ru-Shang Hsiao  
No.9, Lane 29, Zihciang S. Rd.  
Jhubei City, Hsinchu County  
302, Taiwan (R.O.C.)

Assignor(s):

Ling-Sung Wang  
No.3, Alley 117, Lane 851, Sec. 2, Zhonghua W. Rd.  
West Central Dist., Tainan City  
70063, Taiwan (R.O.C.)

Assignor(s):

Chih-Mu Huang  
No.213, Xiwei  
Shanhua Dist., Tainan City  
741, Taiwan (R.O.C.)

Assignor(s):

Cing-Yao Chan  
3F., No.42-2, Ln. 325, Yuanyuan Rd.  
Nuannuan Dist., Keelung City  
205, Taiwan (R.O.C.)

Assignor(s):

Chun-Ying Wang  
Rm. 8, 17F., No.28, Ln. 8, Beiyuan St.  
North Dist., Tainan City  
704, Taiwan

Assignor(s):

Jen-Pan Wang  
No. 49-10, Yuxiao Rd.  
East Dist., Tainan  
701, Taiwan (R.O.C.)

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Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.  
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park  
Hsin-Chu, Taiwan 300-77  
Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

**"SANDWICH EPI CHANNEL FOR DEVICE ENHANCEMENT"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

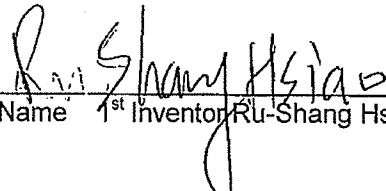
NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be

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granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2014.2.27  
Date

  
Name 1<sup>st</sup> Inventor Ru-Shang Hsiao

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2014, 3.11  
Date

Ling-Sung Wang  
Name 2<sup>nd</sup> Inventor Ling-Sung Wang

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2014, 02, 27

Date

Chih-Mu Huang

Name 3<sup>rd</sup> Inventor Chih-Mu Huang

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Date

Cing - Yao Chan

Name 4<sup>th</sup> Inventor Cing-Yao Chan



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2014.3.4  
Date

Chun Ying Wang  
Name 5<sup>th</sup> Inventor Chun-Ying Wang

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Feb. 27: 2014  
Date

Jen-Pan Wang  
Name 6<sup>th</sup> Inventor Jen-Pan Wang